Attachment to Interview Summary of August 18, 2009:

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DATE: August 13, 2009

CLIENT NO.: 21581-00456-US

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PAGES (Including Cover Sheet): 6 **HARD COPY TO FOLLOW:** [ ] YES [x] NO

MESSAGE: Attached are the proposed admendments to the claims to be discussed at our interview on Tuesday, August 18, 2009 at 10 am concerning USSN 10/541,586.

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Application No.: 10/541,586 Docket No.: 21581-00456-US

AMENDMENTS TO THE CLAIMS

This Listing of Claims will replace all prior versions and listings of claims in this application.

Please cancel claim 9 without prejudice or disclaimer.

Listing of Claims:

1. (Currently Amended) A curable resin composition, which contains an epoxy resin, ~~a high molecular polymer having~~ an epoxy group containing acrylic resin having a weight average molecular weight of 10,000 or higher and a curing agent for an epoxy resin, no phase separation structure being observed in a matrix of a resin when a cured product is dyed with a heavy metal and observed with a transmission electron microscope,

wherein the ~~high molecular polymer having an~~ epoxy group containing acrylic resin having a weight average molecular weight of 10,000 or higher has an epoxy equivalent of 200 to 1000.

2. (Original) The curable resin composition according to claim 1, wherein the cured product has a single tanδ peak in viscoelasticity spectrometry and the temperature of the peak is 120°C or higher.

3. (Previously Presented) The curable resin composition according to claim 1, wherein the cured product has a swelling ratio of 50% or less measured in a dimethyl sulfoxide solution heated at 120°C.

4. (Previously Presented) The curable resin composition according to claim 1, wherein extracted water obtained by extracting an eluting component of the cured product with hot water at 110°C has pH not lower than 5.0 and lower than 8.5.

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5. (Previously Presented) The curable resin composition according to claim 1, wherein extracted water obtained by extracting an eluting component of the cured product with hot water at 110°C has an electric conductivity of 100 μS/cm or lower.

6. (Previously Presented) The curable resin composition according to claim 1, wherein the cured product has a dielectric constant of 3.5 or lower and a dielectric loss tangent of 0.02 or lower.

7. (Previously Presented) The curable resin composition according to claim 1, wherein the epoxy resin is an epoxy resin having a polycyclic hydrocarbon skeleton in the main and no inorganic filler is contained.

8. (Original) The curable resin composition according to claim 7, wherein the epoxy resin having a polycyclic hydrocarbon skeleton in the main chain is an epoxy resin having a dicyclopentadiene skeleton or an epoxy resin having a naphthalene skeleton.

9. (Cancelled)

10. (Cancelled)

11. (Previously Presented) The curable resin composition according to claim 1, wherein the high molecular polymer having an epoxy group is produced by suspension polymerization method.

12. (Previously Presented) The curable resin composition according to claim 1, which further contains a low elastic modulus substance having elastic modulus (G') in a range of $1x10^5$ to $1x10^8$ Pa at 20°C.

13. (Withdrawn) A curable resin composition, which contains an epoxy resin composition obtainable by mixing an epoxy resin having a dicyclopentadiene skeleton, an epoxy resin having a naphthalene skeleton and a curing agent for an epoxy resin, and rubber particles having a core-shell structure, the core having a glass transition temperature of 20°C or lower and the shell having a glass transition temperature of 40°C or higher.

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14. (Original) An adhesive epoxy resin paste, which comprises the curable resin composition according to claim 1.

15. (Original) An interlayer adhesive, which comprises the adhesive epoxy resin paste according to claim 14.

16. (Original) A non-conductive paste, which comprises the adhesive epoxy resin paste according to claim 14.

17. (Original) An underfill, which comprises the adhesive epoxy resin paste according to claim 14.

18. (Previously Presented) An adhesive epoxy resin sheet, which is obtained by forming the curable resin composition according to claim 1, in a sheet form.

19. (Original) The adhesive epoxy resin sheet according to claim 18, wherein a heat-cured product obtained by heat curing at a temperature rising rate of 45°C./min has a storage modulus (G') exceeding $1x10^3$ Pa.

20. (Original) The adhesive epoxy resin sheet according to claim 18, wherein the peak temperature of tanδ based on dynamic viscoelasticity is in a range of -20°C to 40°C before curing and 120°C or higher after curing.

21. (Original) A non-conductive film, which comprises the adhesive epoxy resin sheet according to claim 18.

22. (Original) A die attach film, which comprises the adhesive epoxy resin sheet according to claim 18.

23. (Original) A conductive connection paste, wherein conductive fine particles are contained in the adhesive epoxy resin paste according to claim 14.

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24. (Original) An anisotropic conductive paste, which comprises the conductive connection paste according to claim 23.

25. (Original) A conductive connection sheet, which comprises the adhesive epoxy resin sheet according to claim 18, and conductive fine particles, at least a part of the conductive fine particles being exposed out of the adhesive epoxy resin sheet.

26. (Previously Presented) A conductive connection sheet, which is obtained by embedding conductive fine particles smaller than the thickness of the adhesive epoxy resin sheet in the adhesive epoxy resin sheet according to claim 18.

27. (Original) An anisotropic conductive film, which comprises the conductive connection sheet according to claim 26.

28. (Withdrawn) A conductive connection sheet, which is formed by a pressure sensitive adhesive resin sheet comprising a pressure sensitive resin composition containing a resin provided with a pressure sensitive adhesive property by addition of a plasticizer and an epoxy resin having a naphthalene skeleton in liquid phase at normal temperature and conductive fine particles, the pressure sensitive adhesive resin sheet having a peak temperature of tanδ based on dynamic viscoelasticity in a range of -20°C to 40°C before curing and 120°C or higher after curing and the conductive fine particles being arranged at any positions of the pressure sensitive adhesive resin sheet and at least a part of the conductive fine particles being exposed out of the pressure sensitive adhesive resin sheet.

29. (Withdrawn) The conductive connection sheet according to claim 28, wherein the pressure sensitive adhesive resin sheet after curing has an elongation percentage of 5% or lower after a pressure cooker test carried out under conditions of a temperature of 120°C and a humidity of 85% RH for 12 hours.

30. (Previously Presented) A flip chip tape, which comprises a conductive connection sheet according to claim 25.

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31. (Previously Presented) An electronic component joined body, which is obtained by joining a bump-shaped projected electrode of an electronic part to another electrode in electrically connected state by a curable resin composition according to claim 1.

32. (Currently Amended) An electronic component joined body, which is obtained by joining at least one ~~kind~~ member circuit substrate selected from a group consisting of a metal lead frame, a ceramic substrate, a resin substrate, a silicon substrate, a compound semiconductor substrate, and a glass substrate by any of the curable resin composition according to claim 1.

33. (Original) The electronic component joined body according to claim 32, wherein the resin substrate is a glass epoxy substrate, a bismaleimidetriazine substrate or a polyimide substrate.

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